



REVISIONS				
REV.	ECN	DESCRIPTION	DATE	APPROVED
C		INITIAL RELEASE	APR18/06	ML
D		PCB SOLDERPAD WIDTH REVISED FROM .010" TO .014"	FEB18/07	JL
E		TOLERANCE ADDED TO PCB HOLE & LOCATING PIN	FEB27/07	JL
F		FSI-R26-3000 ADDED	APR05/07	JL
G		DIAM. REG. DIM'S ADDED, TOLERANCE ADDED TO .472	AUG09/07	JL
H		HOUSING MODIFIED	AUG21/07	JL
J		IMPERIAL UNITS REMOVED	OCT4/07	JL

PART NUMBER	PACKAGING	CONTACT PLATING
FS1-R26-2000	TAPE AND REEL	30μ" GOLD OVER 50μ" NICKEL IN CONTACT AREAS 100μ" MATTE TIN OVER 50μ" NICKEL IN SOLDER AREAS
FS1-R26-3000		15μ" GOLD OVER 50μ" NICKEL IN CONTACT AREAS 100μ" MATTE TIN OVER 50μ" NICKEL IN SOLDER AREAS

- NOTES
- MATERIAL:  
HOUSING: SOLDER REFLOW PROCESS COMPATIBLE LCP, UL94V-0  
CONTACTS: PHOSPHOR BRONZE
  - ROHS COMPLIANT
  - PERFORMANCE:  
ELECTRICAL: 0.5 AMPS MAX. PER CONTACT  
MECHANICAL: 250 MATING CYCLES MINIMUM
  - COMPLIES WITH SFF-8086



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:		APPROVALS		DATE	Amphenol Canada Corp.	
DIGITALS	ANGLES	DRAWN	YK	15/FEB/06	TITLE	
X ± 0.25	± 2°	DESIGNED	YK	15/FEB/06	SFF, 26 POSITION CONNECTOR	
XX ± 0.13		CHECKED				
MATERIAL FINISH		QA APP'D				
ENG. FILE NO.	EAAPPD				REV.	J
CODE IDENT. NO.	03554	ENGR. APP'D			SCALE	NTS
					PRECISE	SFF
						SHEET 1 OF 1

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RECOMMENDED PCB LAYOUT

DO NOT SCALE DRAWING

KEEP OUT ZONE IN HATCHED AREAS  
NO TRACES OR INK MARKING ALLOWED